

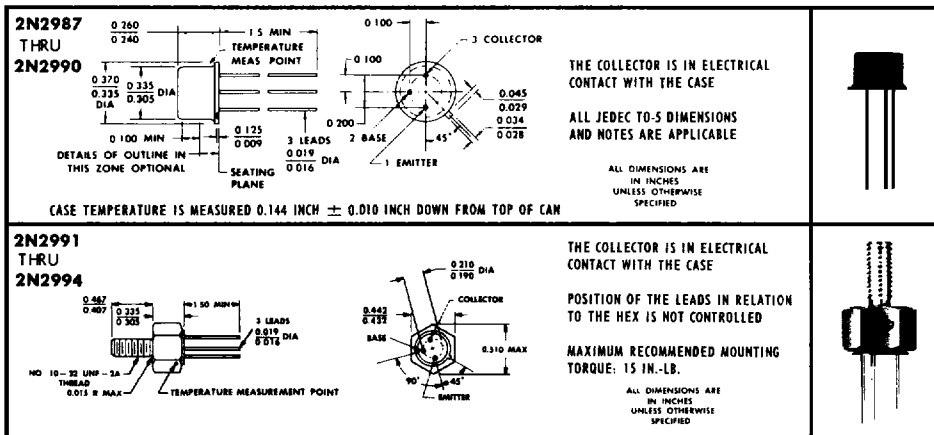
# TYPES 2N2987 THRU 2N2994 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPES 2N2987 THRU 2N2994  
BULLETIN NO. DLS-6810508, DECEMBER 1968

## HIGH-FREQUENCY INTERMEDIATE-POWER TRANSISTORS

- 15 Watts at 100°C Case Temperature
- Typ  $V_{CE(sat)}$  of 0.2 V at 200 mA
- Typ  $V_{BE}$  of 0.8 V at 200 mA
- Typ  $f_T$  of 50 MHz at 10 V, 100 mA

### \* mechanical data



### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	2N2987	2N2988	2N2991	2N2992
	2N2989	2N2990	2N2993	2N2994
* Collector-Base Voltage	95 V	155 V	95 V	155 V
* Collector-Emitter Voltage (See Note 1)	80 V	100 V	80 V	100 V
* Emitter-Base Voltage	← 7 V →			
* Continuous Collector Current	← 1 A →			
Peak Collector Current (See Note 2)	← 1.5 A →			
* Continuous Base Current	← 0.2 A →			
Safe Operating Region at (or below) 100°C Case Temperature	See Figure 10			
* Continuous Device Dissipation at (or below) 100°C Case Temperature (See Note 3)	← 15 W →			
* Continuous Device Dissipation at (or below) 25°C Free-Air Temperature (See Note 4)	← 1 W →		← 2 W →	
* Operating Case Temperature Range	← -65°C to 200°C →			
* Storage Temperature Range	← -65°C to 200°C →			
* Lead Temperature 1/8 Inch from Case for 10 Seconds	← 230°C →			

- NOTES: 1. This value applies between 1 mA and 30 mA collector current when the base-emitter diode is open-circuited.  
 2. This value applies for  $t_p \leq 0.3$  ms, duty cycle  $\leq 10\%$ .  
 3. Derate linearly to 200°C case temperature at the rate of 150 mW/deg.  
 4. Derate linearly to 200°C free-air temperature at the rate of 5.7 mW/deg for the 2N2987 through 2N2990 and 11.4 mW/deg for the 2N2991 through 2N2994.

\*Indicates JEDEC registered data

# TYPES 2N2987 THRU 2N2994

## N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

\*electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	2N2987	2N2988	2N2989	2N2990	UNIT	
		2N2991	2N2992	2N2993	2N2994		
		MIN	MAX	MIN	MAX	MIN	MAX
$V_{(BR)CEO}$ Collector-Emitter Breakdown Voltage	$I_C = 30 \text{ mA}$ , $I_B = 0$ , See Note 5	80	100	80	100		V
$I_{CEO}$ Collector Cutoff Current	$V_{CE} = 50 \text{ V}$ , $I_B = 0$ $V_{CE} = 90 \text{ V}$ , $I_B = 0$	0.1		0.1		0.1	$\mu\text{A}$
$I_{CEV}$ Collector Cutoff Current	$V_{CE} = 90 \text{ V}$ , $V_{BE} = -1.5 \text{ V}$	25		25			nA
	$V_{CE} = 150 \text{ V}$ , $V_{BE} = -1.5 \text{ V}$		25		25		$\mu\text{A}$
	$V_{CE} = 90 \text{ V}$ , $V_{BE} = -1.5 \text{ V}$ , $T_C = 175^\circ\text{C}$	15		15			$\mu\text{A}$
	$V_{CE} = 150 \text{ V}$ , $V_{BE} = -1.5 \text{ V}$ , $T_C = 175^\circ\text{C}$		15		15		nA
$I_{EBO}$ Emitter Cutoff Current	$V_{EB} = 7 \text{ V}$ , $I_C = 0$	25	25	25	25		nA
$h_{FE}$ Static Forward Current Transfer Ratio	$V_{CE} = 5 \text{ V}$ , $I_C = 1 \text{ mA}$	20	20	40	40		
	$V_{CE} = 5 \text{ V}$ , $I_C = 200 \text{ mA}$ , See Notes 5 and 6	25	75	25	75	60	120
	$V_{CE} = 5 \text{ V}$ , $I_C = 500 \text{ mA}$ , See Notes 5 and 6	20	20	40	40		
	$V_{CE} = 10 \text{ V}$ , $I_C = 100 \text{ mA}$ , See Notes 5 and 6	25	25	50	50		
	$V_{CE} = 5 \text{ V}$ , $I_C = 200 \text{ mA}$ , $T_C = -55^\circ\text{C}$ , See Notes 5 and 6	10	10	20	20		
$V_{BE}$ Base-Emitter Voltage	$V_{CE} = 5 \text{ V}$ , $I_C = 200 \text{ mA}$ , See Notes 5 and 6	0.9	0.9	0.9	0.9		V
	$I_B = 20 \text{ mA}$ , $I_C = 200 \text{ mA}$ , See Notes 5 and 6	1	1	1	1		V
	$I_B = 50 \text{ mA}$ , $I_C = 500 \text{ mA}$ , See Notes 5 and 6	1.4	1.4	1.4	1.4		V
$V_{CE(sat)}$ Collector-Emitter Saturation Voltage	$I_B = 20 \text{ mA}$ , $I_C = 200 \text{ mA}$ , See Notes 5 and 6	0.8	0.8	0.8	0.8		V
	$I_B = 50 \text{ mA}$ , $I_C = 500 \text{ mA}$ , See Notes 5 and 6	3	3	3	3		V
$h_{fe}$ Small-Signal Common-Emitter Forward Current Transfer Ratio	$V_{CE} = 10 \text{ V}$ , $I_C = 100 \text{ mA}$ , $f = 1 \text{ kHz}$	25	85	25	85	50	170
$ h_{fe} $ Small-Signal Common-Emitter Forward Current Transfer Ratio	$V_{CE} = 10 \text{ V}$ , $I_C = 100 \text{ mA}$ , $f = 30 \text{ MHz}$	1	1	1	1		
$C_{obo}$ Common-Base Open-Circuit Output Capacitance	$V_{CB} = 10 \text{ V}$ , $I_E = 0$ , $f = 1 \text{ MHz}$	50	50	50	50		pF

NOTES: 5. These parameters must be measured using pulse techniques.  $t_p = 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

\*Indicates JEDEC registered data

### thermal characteristics

PARAMETER	2N2987	2N2991	UNIT
	THRU 2N2990	THRU 2N2994	
	MAX	MAX	
$\theta_{J-C}$ Junction-to-Case Thermal Resistance	6.67	6.67	deg/W
$\theta_{J-A}$ Junction-to-Free-Air Thermal Resistance	175	87.5	

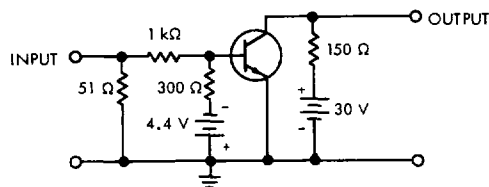
# TYPES 2N2987 THRU 2N2994 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

switching characteristics at 25°C case temperature

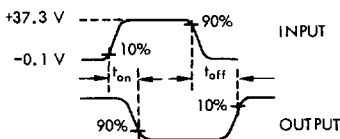
PARAMETER	TEST CONDITIONS†	TYP	UNIT
$t_{on}$ Turn-On Time	$I_C = 200 \text{ mA}$ , $I_{B(1)} = 20 \text{ mA}$ , $I_{B(2)} = -20 \text{ mA}$ ,	0.14	$\mu\text{s}$
$t_{off}$ Turn-Off Time	$V_{BE(off)} = -3.4 \text{ V}$ , $R_L = 150 \Omega$ , See Figure 1	2.6	

†Voltage and current values shown are nominal; exact values vary slightly with transistor parameters

## PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

FIGURE 1

- NOTES:
- The input waveform is supplied by a generator with the following characteristics:  $t_r \leq 15 \text{ ns}$ ,  $t_f \leq 15 \text{ ns}$ ,  $Z_{out} = 50 \Omega$ ,  $t_p = 10 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
  - Waveforms are monitored on an oscilloscope with the following characteristics:  $t_r \leq 15 \text{ ns}$ ,  $R_{in} \geq 10 \text{ M}\Omega$ ,  $C_{in} \leq 11.5 \text{ pF}$ .
  - Resistors must be noninductive types.
  - The d-c power supplies may require additional bypassing in order to minimize ringing.

# TYPES 2N2987 THRU 2N2994 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

## TYPICAL CHARACTERISTICS

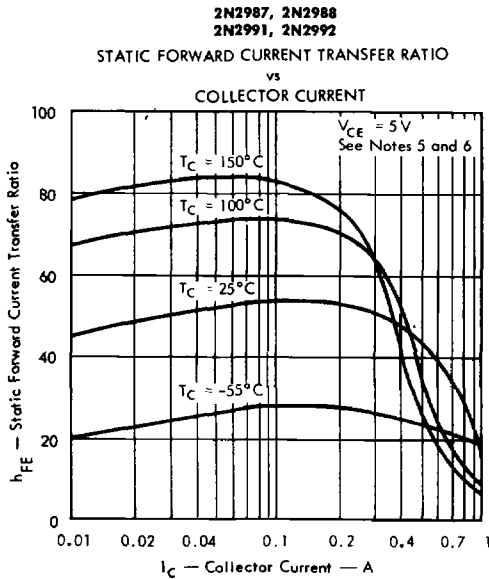


FIGURE 2

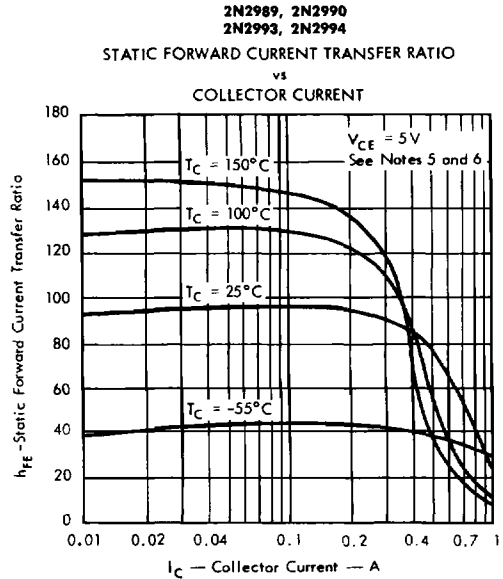


FIGURE 3

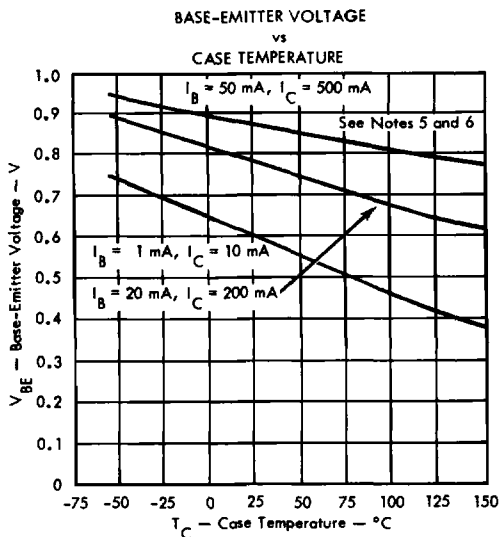


FIGURE 4

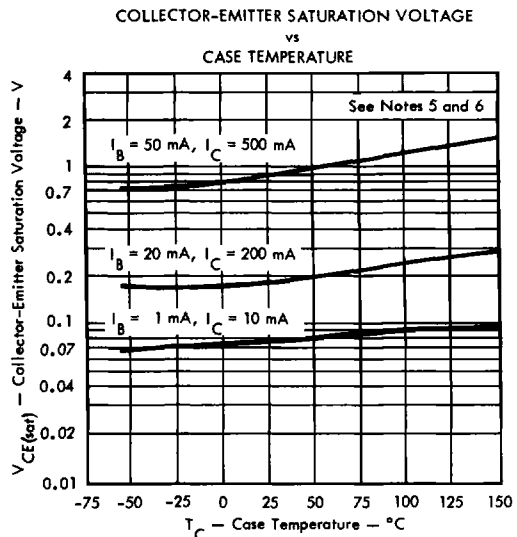


FIGURE 5

NOTES: 5. These parameters must be measured using pulse techniques.  $t_p = 300\ \mu s$ , duty cycle  $\leq 2\%$ .

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

# TYPES 2N2987 THRU 2N2994 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

## TYPICAL CHARACTERISTICS

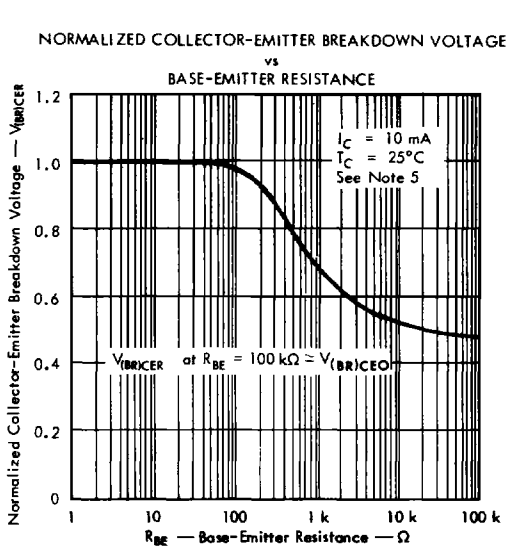


FIGURE 6

2N2987, 2N2988  
2N2991, 2N2992

SMALL-SIGNAL COMMON-EMITTER  
FORWARD CURRENT TRANSFER RATIO  
vs  
FREQUENCY

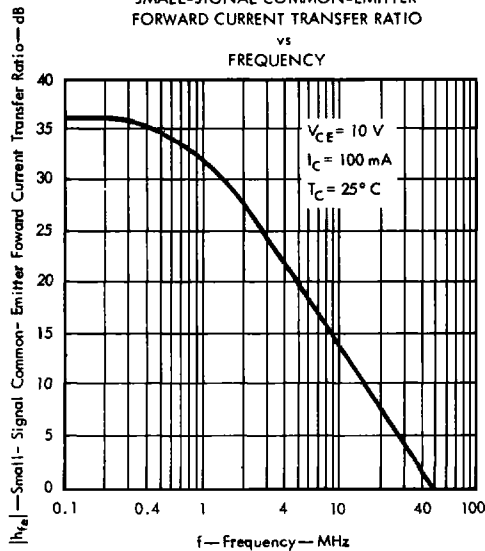


FIGURE 8

NOTE 5: This parameter must be measured using pulse techniques.  $t_p = 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

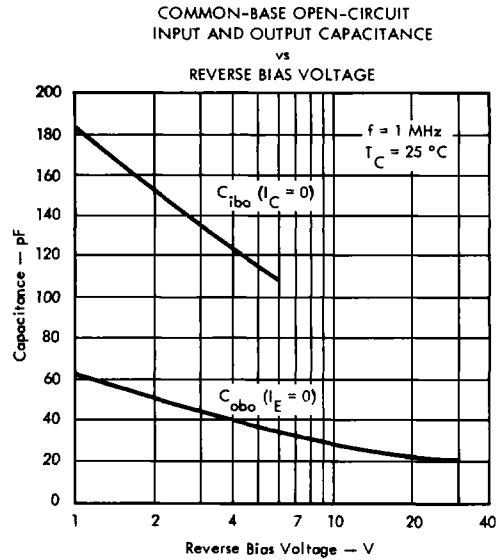


FIGURE 7

2N2989, 2N2990  
2N2993, 2N2994

SMALL-SIGNAL COMMON-EMITTER  
FORWARD CURRENT TRANSFER RATIO  
vs  
FREQUENCY

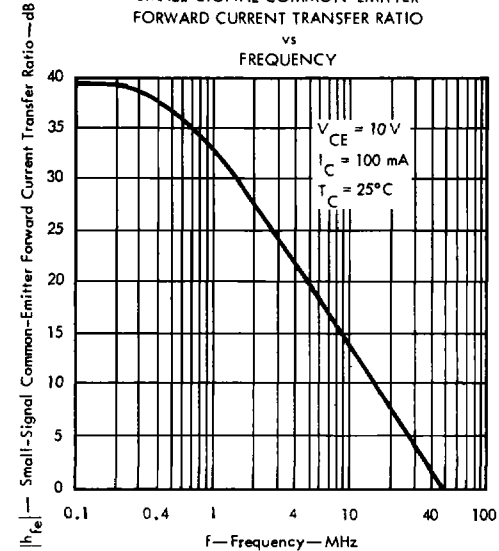


FIGURE 9

# TYPES 2N2987 THRU 2N2994 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

## MAXIMUM SAFE OPERATING REGION

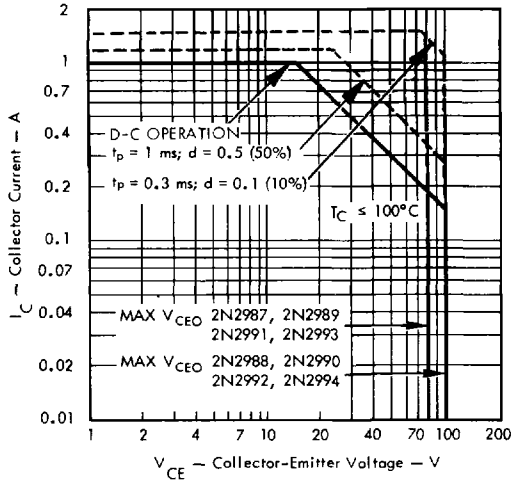


FIGURE 10

## THERMAL INFORMATION

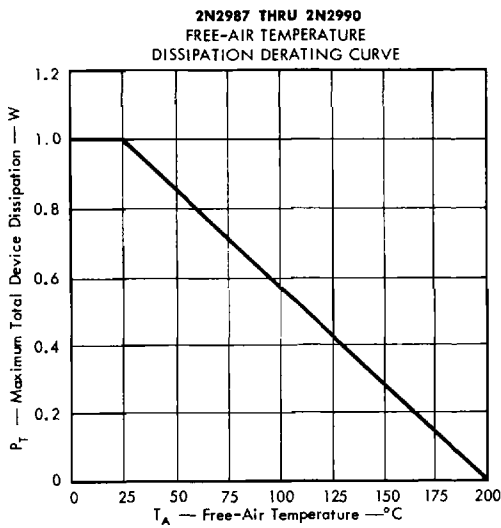


FIGURE 11

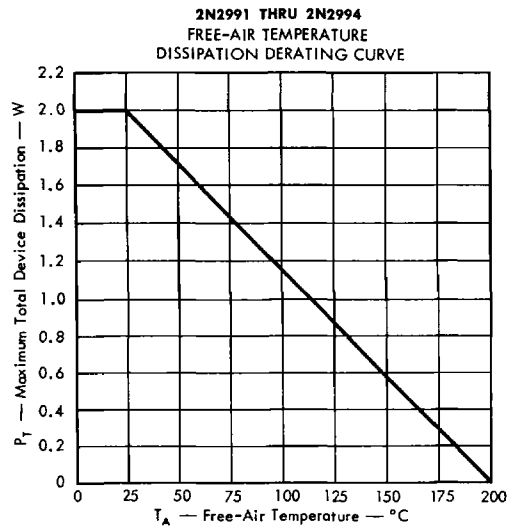


FIGURE 12

# TYPES 2N2987 THRU 2N2994 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

## THERMAL INFORMATION

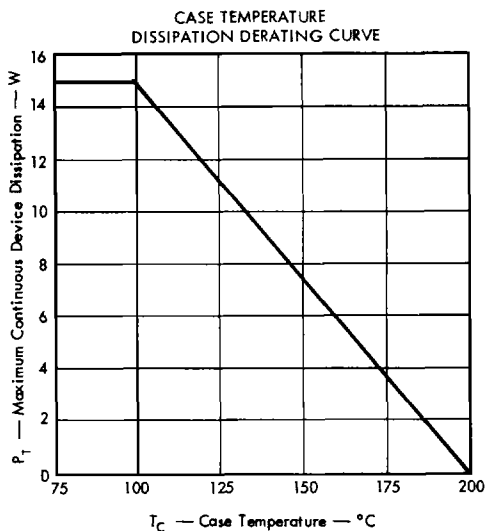


FIGURE 13

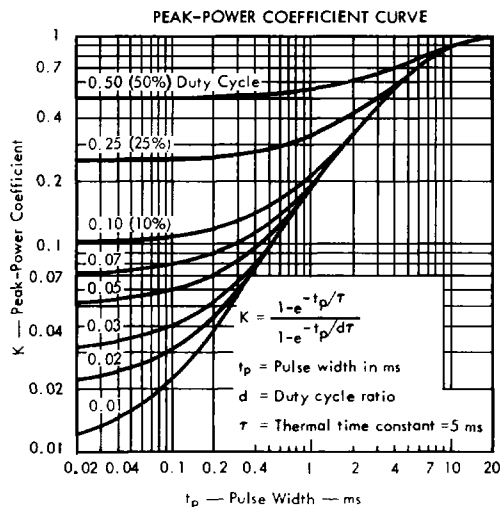


FIGURE 14

### SYMBOL DEFINITION

SYMBOL	DEFINITION	VALUE		UNIT
		2N2987 THRU 2N2990	2N2991 THRU 2N2994	
$P_{T(av)}$	Average Power Dissipation			W
$P_{T(max)}$	Peak Power Dissipation			W
$\theta_{J-A}$	Junction-to-Free-Air Thermal Resistance	175	87.5	deg/W
$\theta_{J-C}$	Junction-to-Case Thermal Resistance	6.67	6.67	deg/W
$\theta_{C-A}$	Case-to-Free-Air Thermal Resistance	168	81	deg/W
$\theta_{C-HS}$	Case-to-Heat-Sink Thermal Resistance			deg/W
$\theta_{HS-A}$	Heat-Sink-to-Free-Air Thermal Resistance			deg/W
$T_A$	Free-Air Temperature			°C
$T_C$	Case Temperature			°C
$T_{J(av)}$	Average Junction Temperature	≤ 200		°C
$T_{J(max)}$	Peak Junction Temperature	≤ 200		°C
K	Peak-Power Coefficient	See Figure 14		
$t_p$	Pulse Width			ms
$t_x$	Pulse Period			ms
d	Duty-Cycle Ratio ( $t_p/t_x$ )			

Equation No. 1 — Application: d-c power dissipation, heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-C} + \theta_{C-HS} + \theta_{HS-A}} \text{ for } 100^\circ\text{C} \leq T_C \leq 200^\circ\text{C} \text{ as in figure 13}$$

Equation No. 2 — Application: d-c power dissipation, no heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-A}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Equation No. 3 — Application: Peak power dissipation, heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K\theta_{J-C}} \text{ for } 100^\circ\text{C} \leq T_C \leq 200^\circ\text{C}$$

Equation No. 4 — Application: Peak power dissipation, no heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d\theta_{C-A} + K\theta_{J-C}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Example — Find  $P_{T(max)}$  (design limit)

OPERATING CONDITIONS:

$$\theta_{C-HS} + \theta_{HS-A} = 7 \text{ deg/W (from information supplied with heat sink)}$$

$$T_{J(av)} \text{ (design limit)} = 200^\circ\text{C}$$

$$T_A = 50^\circ\text{C}$$

$$d = 10\% (0.1)$$

$$t_p = 0.1 \text{ ms}$$

Solution:

From Figure 14, Peak-Power Coefficient

$$K = 0.11 \text{ and by use of equation No. 3}$$

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K\theta_{J-C}}$$

$$P_{T(max)} = \frac{200 - 50}{0.1(7) + 0.11(6.67)} = 105 \text{ W}$$